



Patent

Customer No.: 31561  
Docket No. 10796-US-PA  
Application No.: 10/710,344

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Ho et al.  
Application No. : 10/710,344  
Filed : July 2, 2004  
For : CHIP PACKAGE STRUCTURE WITH DUAL HEAT SINKS  
Art Unit : 2826  
Examiner : QUINTO, KEVIN V

**TRANSMITTAL LETTER**

002-1-571-273-2885

(Via fax: 1+2 pages)

Assistant Commissioner for Patents  
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated September 9, 2005, transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Please charge the fee in the amount of \$1700.00 for Issue Fee and Publication Fee to Account No. 50-2620 (Order No.: 10796-US-PA).

Please be advised that the title of the invention should be amended as shown above according to the response to the first Office Action mailed June 27, 2005.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date:

Dec. 7, 2005

By:

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